PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Chiung-Han Yeh	02/20/2009
Chen-Pin Hsu	02/20/2009
Ming-Yuan Wu	02/20/2009
Kong-Beng Thei	02/20/2009
Harry Chuang	02/20/2009

RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC")	
Street Address:	No. 8, Li-Hsin Rd. 6	
Internal Address:	Science-Based Industrial Park	
City:	Hsin-Chu	
State/Country:	TAIWAN	
Postal Code:	300-77	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13245494

CORRESPONDENCE DATA

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via US Mail.

Correspondent Name: Haynes and Boone, LLP

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ATTORNEY DOCKET NUMBER: 2008-0506-D / 24061.1990

PATENT

REEL: 026969 FRAME: 0598

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NAME OF SUBMITTER:	Kelly Gehrke Lyle
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PATENT REEL: 026969 FRAME: 0599

Docket No.: 2008-0506 / 24061.1143

Customer No.: 42717

ASSIGNMENT

WHI	EREAS, we,		
(1)	Chiung-Han Yeh	of	No. 214, Dawu Street, North District Tainan City 704, Taiwan, R.O.C.
(2)	Chen-Pin Hsu	of	No. 18, Huangnitang Road, Neighbor 7, Huangtan Village Longtan Township, Taoyuan, Taiwan, R.O.C.
(3)	Ming-Yuan Wu	of	No. 3, Dongshih Street Hsinchu City 300, Taiwan, R.O.C.
(4)	Kong-Beng Thei	of	No. 186, Nan-Kang Road, Pao-Shan Village Hsin-Chu Country, Taiwan, R.O.C.
(5)	Harry Chuang	of	18-59 Lane 85, Fu-Chuan Street Hsin-Chu City 300, Taiwan, R.O.C.

have invented certain improvements in

PHOTORESIST ETCH BACK METHOD FOR GATE LAST PROCESS

for which we have executed an application for Letters Patent of the United States of America,

<u>X</u>	of even date filed herewith; and	
	filed on $\frac{6-3-2009}{2}$ and assigned application number $\frac{12}{477618}$: and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said

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invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name:	Chiung-Han Yeh
Residence Address:	No. 214, Dawu Street, North District Tainan City 704, Taiwan, R.O.C.
Dated: //w	Chiung - Han Yeh Inventor Signature
Inventor Name:	Chen-Pin Hsu
Residence Address:	No. 18, Huangnitang Road, Neighbor 7, Huangtan Village Longtan Township, Taoyuan, Taiwan, R.O.C.
Dated:	109 Chen-Ch, How
Inventor Name:	Ming-Yuan Wu
Residence Address:	No. 3, Dongshih Street Hsin Chu City 300, Taiwan, R.O.C.
Dated: 2/20 / C	Inventor fignature

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Inventor Name:

Kong-Beng Thei

Residence Address:

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Hsin-Chu Country, Taiwan, R.O.C.

Dated:

Inventor Signature

Inventor Name:

Harry Chuang

Residence Address:

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Dated: 2-20-2009

Inventor Signature

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RECORDED: 09/26/2011

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